

Type number	Package	Package description	Total product weight
74ALVCH16600DGG	SOT364-1	TSSOP56	218.47765 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935262545518	6	2	260	30 s	2	240	20 s	3	Nijmegen, Netherlands; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.01602	80.10000	0.00733
	Polymer	Resin system	Proprietary	0.00398	19.90000	0.00182
		subTotal		0.02000	100.00000	0.00915
Die	Doped silicon	Silicon (Si)	7440-21-3	3.15233	100.00000	1.44286
		subTotal		3.15233	100.00000	1.44286
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	55.64890	97.00000	25.47121
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	1.72110	3.00000	0.78777
		subTotal		57.37000	100.00000	26.25898
Mould Compound	Filler	Misc. Silica compounds (generic)	14808-60-7	136.29000	88.50000	62.38167
	Flame retardant	Non hazardous	Proprietary	4.62000	3.00000	2.11463
	Polymer	Epoxy resin system	Proprietary	13.09000	8.50000	5.99146
		subTotal		154.00000	100.00000	70.48776
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.03150	1.00000	0.01442
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	3.05550	97.00000	1.39854
		Palladium (Pd)	7440-05-3	0.06300	2.00000	0.02884
		subTotal		3.15000	100.00000	1.44180
Wire	Pure metal	Gold (Au)	7440-57-5	0.77746	99.00000	0.35585
		Palladium (Pd)	7440-05-3	0.00785	1.00000	0.00359
		subTotal		0.78531	100.00000	0.35944

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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